SGLS345 - JUNE 2006

- Controlled Baseline
 - One Assembly/Test Site, One Fabrication Site
- Extended Temperature Performance of -55°C to 125°C
- Enhanced Diminishing Manufacturing Sources (DMS) Support
- Enhanced Product-Change Notification
- Qualification Pedigree[†]
- One-Half V_I Virtual Ground for Analog Systems
- Micropower Operation . . . 170 μA Typ,
 V_I = 5 V
- Wide V₁ Range . . . 4 V to 40 V
- High Output-Current Capability
 - Source . . . 20 mA Typ
 - Sink . . . 20 mA Typ

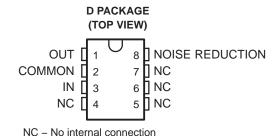
description/ordering information

In signal-conditioning applications utilizing a single power source, a reference voltage equal to one-half the supply voltage is required for termination of all analog signal grounds. TI presents a precision virtual ground whose output voltage is always equal to one-half the input voltage—the TLE2426 rail splitter.

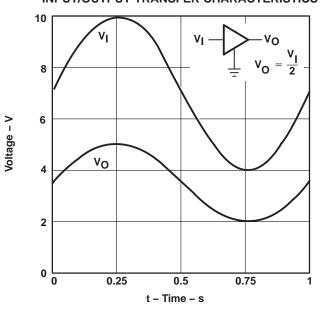
The unique combination of a high-performance, micropower operational amplifier and a precisiontrimmed divider on a single silicon chip results in a precise V_O/V_I ratio of 0.5 while sinking and sourcing current. The TLE2426 provides a lowimpedance output with 20 mA of sink and source capability, while drawing less than 280 µA of supply current over the full input range of 4 V to 40 V. A designer need not pay the price in terms of board space for a conventional signal ground consisting of resistors, capacitors, operational amplifiers, and voltage references. For increased performance, the 8-pin package provides a noise-reduction pin. With the addition of an external capacitor (CNR), peak-to-peak noise is reduced, while line ripple rejection is improved.

- Excellent Output Regulation
 - -102 μ V Typ at I_O = 0 mA to -10 mA
 - $-49 \mu V$ Typ at $I_O = 0$ mA to 10 mA
- Low-Impedance Output . . . 0.0075 Ω Typ
- Noise Reduction Pin

† Component qualification in accordance with JEDEC and industry standards to ensure reliable operation over an extended temperature range. This includes, but is not limited to, Highly Accelerated Stress Test (HAST) or biased 85/85, temperature cycle, autoclave or unbiased HAST, electromigration, bond intermetallic life, and mold compound life. Such qualification testing should not be viewed as justifying use of this component beyond specified performance and environmental limits.



INPUT/OUTPUT TRANSFER CHARACTERISTICS



Initial output tolerance for a single 5-V or 12-V system is better than 1% over the full 40-V input range. Ripple rejection exceeds 12 bits of accuracy. Whether the application is for a data-acquisition front end, analog signal termination, or simply a precision voltage reference, the TLE2426 eliminates a major source of system error.



Please be aware that an important notice concerning availability, standard warranty, and use in critical applications of Texas Instruments semiconductor products and disclaimers thereto appears at the end of this data sheet.



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ORDERING INFORMATION

TA	PACKA	GE†	ORDERABLE PART NUMBER	TOP-SIDE MARKING
-55°C to 125°C	SOIC (D)	Tape and reel	TLE2426MDREP	2426EP

[†] Package drawings, standard packing quantities, thermal data, symbolization, and PCB design guidelines are available at www.ti.com/sc/package.

absolute maximum ratings over operating free-air temperature (unless otherwise noted)†

Continuous input voltage, V _I	
Continuous filter trap voltage	
Output current, I _O	±80 mA
Duration of short-circuit current at (or below) 25°C (see Note 1)	Unlimited
Continuous total power dissipation	See Dissipation Rating Table
Operating free-air temperature range, T _A	–55°C to 125°C
Operating junction temperature, T _J (see Note 2)	150°C
Storage temperature range, T _{stg} (see Note 2)	260°C

[†] Stresses beyond those listed under "absolute maximum ratings" may cause permanent damage to the device. These are stress ratings only, and functional operation of the device at these or any other conditions beyond those indicated under "recommended operating conditions" is not implied. Exposure to absolute-maximum-rated conditions for extended periods may affect device reliability.

- NOTES: 1. The output may be shorted to either supply. Temperature and/or supply voltages must be limited to ensure that the maximum dissipation rating is not exceeded.
 - 2. Long-term high-temperature storage and/or usage at the absolute maximum ratings may result in a reduction of overall device life. See http://www.ti.com/ep_quality for additional information on enhanced plastic packaging.

DISSIPATION RATING TABLE

	PACKAGE	$T_{\mbox{A}} \le 25^{\circ}\mbox{C}$ POWER RATING	DERATING FACTOR ABOVE T _A = 25°C	T _A = 70°C POWER RATING	T _A = 85°C POWER RATING	T _A = 125°C POWER RATING
ı	D	1102 mV	10.3 mW/°C	638.5 mW	484 mW	72.1 mW

recommended operating conditions

	MIN	MAX	UNIT
Input voltage, V _I	4	40	V
Operating free-air temperature, T _A	-55	125	°C



electrical characteristics at specified free-air temperature, $V_I = 5 V$, $I_O = 0$ (unless otherwise noted)

PARAMETER	TEST CONDITIO	ONS	T _A †	MIN	TYP	MAX	UNIT	
	V _I = 4 V			1.98	2	2.02		
	V _I = 5 V	25°C	2.48	2.5	2.52	V		
Output voltage	V _I = 40 V		19.8	20	20.2			
	V _I = 5 V	V _I = 5 V				2.535		
Temperature coefficient of output voltage					25		ppm/°C	
		V _I = 5 V	25°C		170	300		
Supply current	No load	No load				350	μА	
		$V_{ } = 4 \text{ to } 40 \text{ V}$	Full range			400	٦	
		25°C		-0.102	±0.7	mV		
Output voltage regulation (sourcing current)	$I_{O} = 0 \text{ to } -10 \text{ mA}$	Full range			±10			
(Sourcing current)+	$I_{O} = 0 \text{ to } -20 \text{ mA}$	25°C		-0.121	±1.4			
	I _O = 0 to 10 mA	25°C		0.049	±0.5			
Output voltage regulation (sinking current)‡	$I_O = 0$ to 8 mA	Full range			±10	mV		
(Sirking Current)+	I _O = 0 to 20 mA	25°C		0.175	±1.4			
Output impedance‡			25°C		7.5	22.5	mΩ	
Noise-reduction impedance			25°C		110		kΩ	
	Sinking current, VO = 5 V		26					
Short-circuit current	Sourcing current, V _O = 0	25°C	-47			mA		
Output mains valtages mass	£ 4011= 45 40141=	C _{NR} = 0	0500	120		μV		
Output noise voltage, rms	f = 10 Hz to 10 kHz	C _{NR} = 1 μF	25°C	30				
	V 15 0 40/ 1 140 mA	C _L = 0 290						
Output voltage current step response	V_O to 0.1%, $I_O = \pm 10 \text{ mA}$	$C_L = 100 pF$	25°C	275] _		
	V- +- 0.040/	C _L = 0 400			μs			
	V_{O} to 0.01%, $I_{O} = \pm 10 \text{ mA}$	C _L = 100 pF	25°C	390				
Stan raspansa	V _I = 0 to 5 V, V _O to 0.1% C _L = 100 pF		25°C		20			
Step response	$V_I = 0 \text{ to } 5 \text{ V}, V_O \text{ to } 0.01\%$	25 0	120			μs		

[†] Full range is –55°C to 125°C. ‡ The listed values are not production tested.

TLE2426-EP RAIL SPLITTER PRECISION VIRTUAL GROUND SGLS345 – JUNE 2006

electrical characteristics at specified free-air temperature, V_{I} = 12 V, I_{O} = 0 (unless otherwise noted)

PARAMETER	TEST CONDITIO	T _A †	MIN	TYP	MAX	UNIT		
	V _I = 4 V			1.98	2	2.02		
	V _I = 12 V	25°C	5.95	6	6.05	V		
Output voltage	V _I = 40 V		19.8	20	20.2			
	V _I = 12 V	V _I = 12 V				6.075		
Temperature coefficient of output voltage			Full range		35		ppm/°C	
			25°C		195	300		
Supply current	No load	V 44 40 V	25°C			350	μΑ	
		$V_{ } = 4 \text{ to } 40 \text{ V}$	Full range			400		
	1 0 to 40 mA		25°C		-1.48	±10		
Output voltage regulation (sourcing current)‡	$I_{O} = 0 \text{ to } -10 \text{ mA}$	Full range			±10	mV		
(Sourcing current)+	$I_0 = 0 \text{ to } -20 \text{ mA}$	25°C		-3.9	±10			
	I _O = 0 to 10 mA	25°C		2.27	±10			
Output voltage regulation (sinking current)‡	I _O = 0 to 8 mA	Full range			±10	mV		
(Sinking current)+	I _O = 0 to 20 mA	25°C		4.3	±10			
Output impedance [‡]			25°C		7.5	22.5	mΩ	
Noise-reduction impedance			25°C		110		kΩ	
	Sinking current, V _O = 12 V		0500	31				
Short-circuit current	Sourcing current, V _O = 0	25°C	-70			mA		
Output as is a sulfa as a sur-	f 4011-1-40111-	$C_{NR} = 0$	0500	120		.,		
Output noise voltage, rms	f = 10 Hz to 10 kHz	C _{NR} = 1 μF	25°C	30			μV	
	V + 0.40′ I + 1.40 A	C _L = 0	0500		290			
	V_{O} to 0.1%, $I_{O} = \pm 10 \text{ mA}$	C _L = 100 pF	25°C		275			
Output voltage current step response		C _L = 0			400		μs	
	V_{O} to 0.01%, $I_{O} = \pm 10 \text{ mA}$	C _L = 100 pF	25°C		390			
Cton roomana	V _I = 0 to 12 V, V _O to 0.1%	C: 400 mF	2500	12				
Step response	V _I = 0 to 12 V, V _O to 0.01%	C _L = 100 pF	25°C		120		μs	

[†] Full range is –55°C to 125°C.

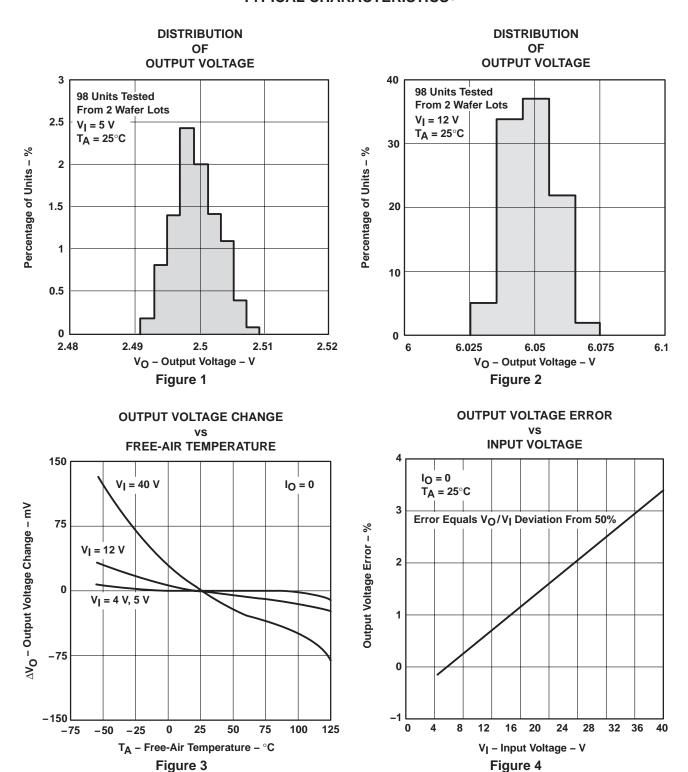
[‡] The listed values are not production tested.

TYPICAL CHARACTERISTICS

Table of Graphs

		FIGURE
Output voltage	Distribution	1, 2
Output voltage change	vs Free-air temperature	3
Output voltage error	vs Input voltage	4
Level bire comment	vs Input voltage	5
Input bias current	vs Free-air temperature	6
Output voltage regulation	vs Output current	7
Output impedance	vs Frequency	8
Obsert einseit sedent sement	vs Input voltage	9, 10
Short-circuit output current	vs Free-air temperature	11, 12
Ripple rejection	vs Frequency	13
Spectral noise voltage density	vs Frequency	14
Output voltage response to output current step	vs Time	15
Output voltage power-up response	vs Time	16
Output current	vs Load capacitance	17

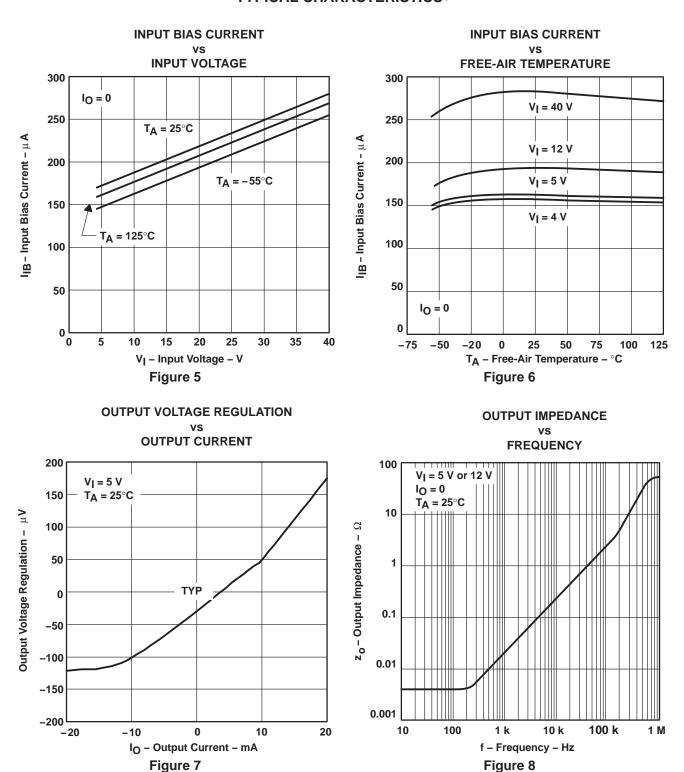
TYPICAL CHARACTERISTICS[†]



[†] Data at high and low temperatures are applicable within the rated operating free-air temperature ranges of the various devices.



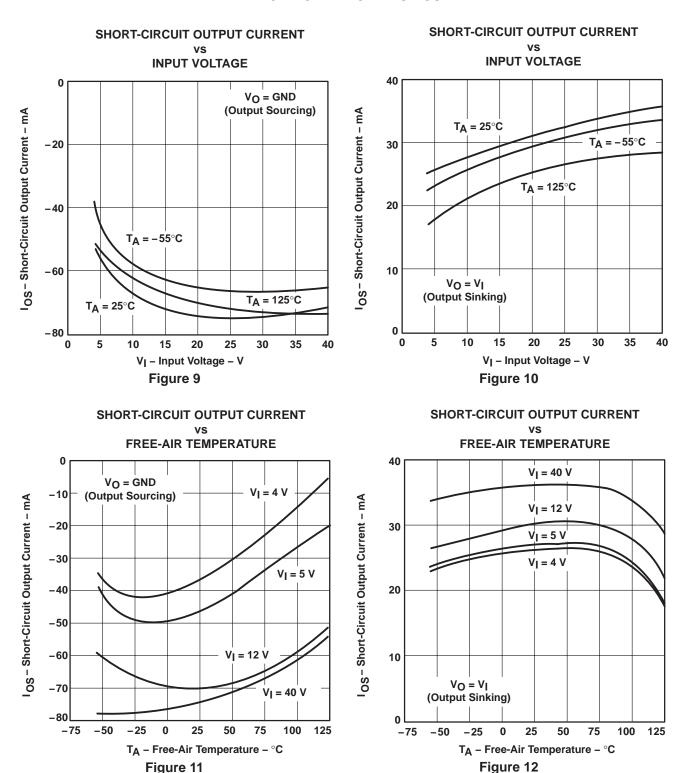
TYPICAL CHARACTERISTICS[†]



[†] Data at high and low temperatures are applicable within the rated operating free-air temperature ranges of the various devices.



TYPICAL CHARACTERISTICS[†]



[†] Data at high and low temperatures are applicable within the rated operating free-air temperature ranges of the various devices.



TYPICAL CHARACTERISTICS

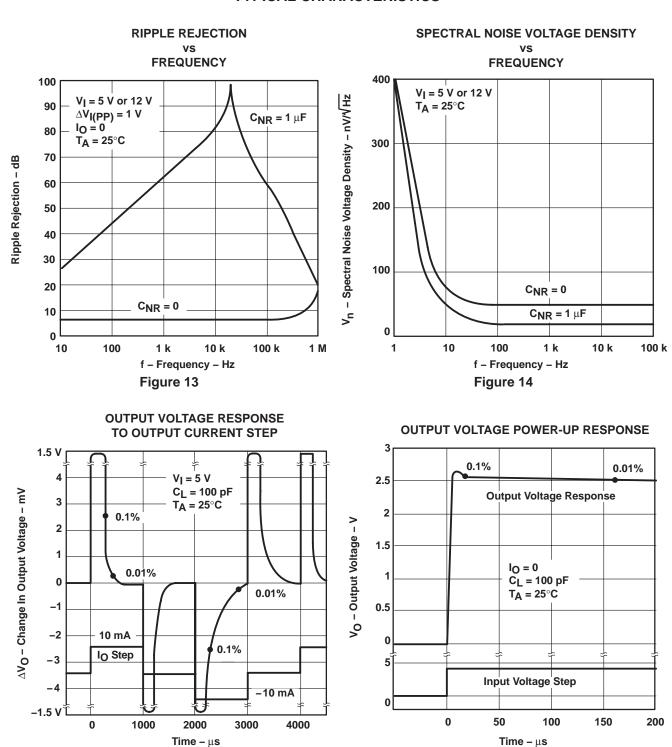




Figure 16

Figure 15

TYPICAL CHARACTERISTICS

STABILITY RANGE **OUTPUT CURRENT**

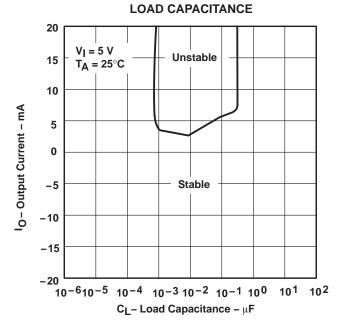


Figure 17

MACROMODEL INFORMATION

TLE2426 OPERATIONAL AMPLIFIER "MACROMODEL" SUBCIRCUIT

```
CREATED USING PARTS RELEASE 4.03 ON 08/21/90 AT 13:51
                SUPPLY VOLTAGE: 5 V
   REV (N/A)
   CONNECTIONS:
                    FILTER
                       INPUT
                           COMMON
                              OUTPUT
.SUBCKT TLE2426
                              5
   C1
          11 12 21.66E-12
   C2
              7 30.00E-12
   C3
          87
              0 10.64E-9
   CPSR
          85 86 15.9E-9
   DCM+
          81 82 DX
   DCM-
          83
             81 DX
   DC
          5
             53 DX
   DE
          54
              5 DX
   DLP
          90
             91 DX
   DLN
          92
             90
                DX
   DP
          4
              3 DX
          84 99 (2,99) 1
   ECMR
                           (3,0) (4,0) 0 .5 .5
(3,4) -16.22E-6 3.24E-6
   EGND
          99
              0 POLY(2)
          85
   EPSR
              0
                POLY(1)
   ENSE
             2 POLY(1)
                           (88,0) 120E-61
   FΒ
          7
             99 POLY(6)
                           VB VC VE VLPVLNVPSR 0 74.8E6 - 10E6 10E6 10E6 - 10E6 74E6
   GA
           6
              0
                11 12 320.4E-6
              6 10 99 1.013E-9
   GCM
           0
         85 86 (85,86)
   GPSR
                           100E-6
   GRC1
          4
             11
                 (4,11) 3.204E-4
           4 12 (4,12) 3.204E-4
   GRC2
   GRE1
          13 10 (13,10) 1.038E-3
   GRE2
          14 10 (14,10)
                           1.038E-3
              0 VLIM 1K
         90
   HT.TM
   HCMR
          80
             1 POLY(2)
                           VCM+
                                 VCM-
                                         0 1E2
                                                   1E2
   IRP
          3
              4 146E-6
   IEE
           3 10 DC 24.05E-6
   IIO
          2
             0.2E - 9
             0 1E - 21
   T 1
          88
   Q1
          11
             89 13 QX
          12 80 14 QX
   02
   R2
          6
              9 100.0E3
          84
             81 1K
   RCM
   REE
          10 99
                 8.316E6
   RN1
          87
              0
                2.55E8
   RN2
          87
             88 11.67E3
   RO1
          8
              5
                63
           7
             99 62
   RO2
   VCM+
          82
             99 1.0
   VCM-
          83
             99
                -2.3
              0 DC 0
   VB
          9
   VC
           3
             53 DC 1.400
   VE
          54
              4 DC 1.400
              8 DC 0
          7
   VLIM
   VLP
          91
              0 DC 30
   VLN
           0 92 DC
                   30
   VPSR
           0 86 DC
                    0
   RFB
             2 1K
   RTN1
              1 220K
          3
   RIN2
          1
              4 220K
.MODEL DX D(IS=800.OE-18)
.MODEL QX PNP(IS=800.OE-18BF=480)
```



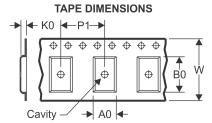
.ENDS

PACKAGE MATERIALS INFORMATION

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TAPE AND REEL INFORMATION





	Dimension designed to accommodate the component width
В0	Dimension designed to accommodate the component length
K0	Dimension designed to accommodate the component thickness
W	Overall width of the carrier tape
P1	Pitch between successive cavity centers

QUADRANT ASSIGNMENTS FOR PIN 1 ORIENTATION IN TAPE



*All dimensions are nominal

Device	Package Type	Package Drawing			Reel Diameter (mm)	Reel Width W1 (mm)	A0 (mm)	B0 (mm)	K0 (mm)	P1 (mm)	W (mm)	Pin1 Quadrant
TLE2426MDREP	SOIC	D	8	2500	330.0	12.4	6.4	5.2	2.1	8.0	12.0	Q1

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*All dimensions are nominal

Device	Package Type	Package Drawing	Pins	SPQ	Length (mm)	Width (mm)	Height (mm)
TLE2426MDREP	SOIC	D	8	2500	367.0	367.0	38.0

D (R-PDSO-G8)

PLASTIC SMALL OUTLINE



NOTES:

- A. All linear dimensions are in inches (millimeters).
- B. This drawing is subject to change without notice.
- Body length does not include mold flash, protrusions, or gate burrs. Mold flash, protrusions, or gate burrs shall not exceed 0.006 (0,15) each side.
- Body width does not include interlead flash. Interlead flash shall not exceed 0.017 (0,43) each side.
- E. Reference JEDEC MS-012 variation AA.



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